

**Features**

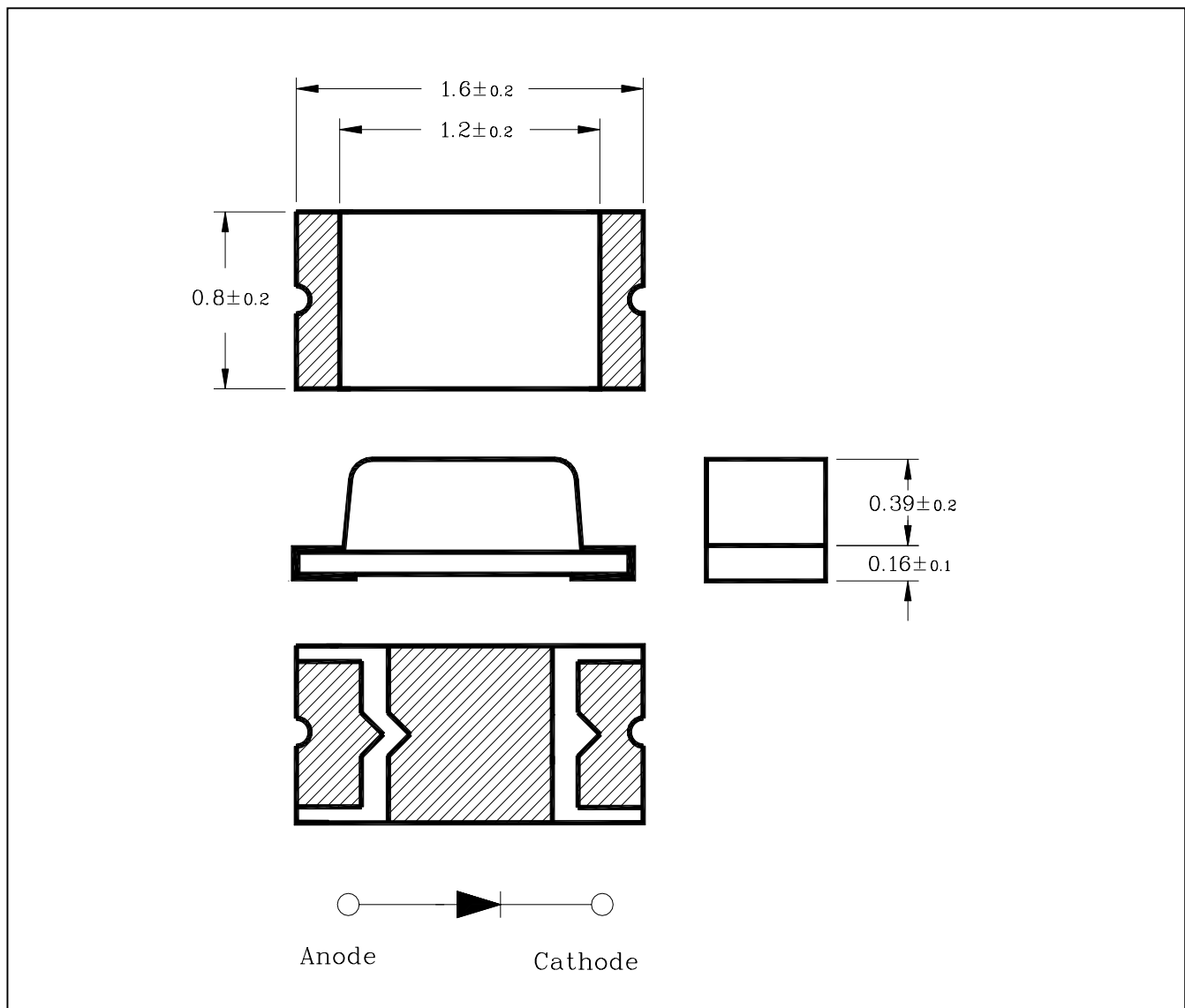
- 1.6mm(L)×0.8mm small size surface mount type
- Thin package of 0.55mm(H) thickness
- Transparent clear lens optic
- Low power consumption type chip LED

**Applications**

- LCD backlighting
- Keypad backlighting
- Symbol backlighting
- Front panel indicator lamp

**Outline Dimensions**

unit : mm



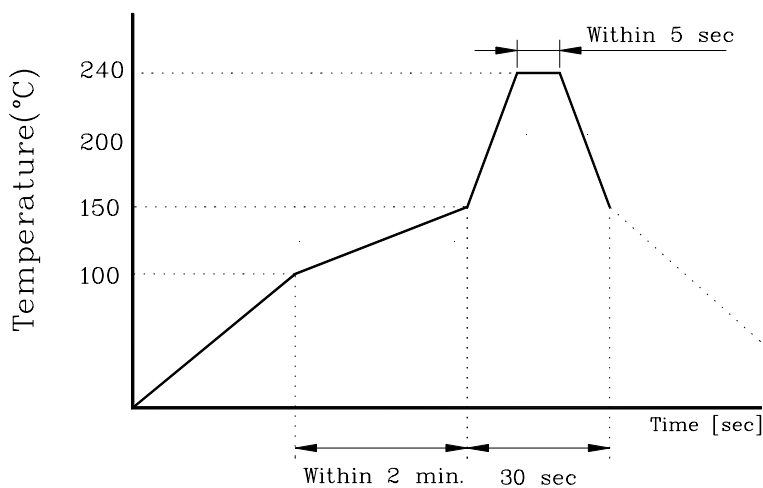
**Absolute maximum ratings**

Characteristic	Symbol	Ratings	Unit
Power Dissipation	$P_D$	70	mW
Forward Current	$I_F$	25	mA
*1Peak Forward Current	$I_{FP}$	50	mA
Reverse Voltage	$V_R$	4	V
Operating Temperature	$T_{opr}$	-25~80	°C
Storage Temperature	$T_{stg}$	-30~100	°C
*2Soldering Temperature	$T_{sol}$	240°C for 5 seconds	

\*1.Duty ratio = 1/16, Pulse width = 0.1ms

\*2.Recommended soldering Temperature Profile

- 2-1) Preheating 100°C to 150°C within 2 minutes Soldering 240°C within 5 seconds
- Gradual cooling (Avoid quenching)



**Electrical Characteristics**

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	$V_F$	$I_F= 20mA$	-	2.1	2.8	V
Luminous Intensity	$I_V$	$I_F= 20mA$	-	3	-	mcd
Peak Wavelength	$\lambda_P$	$I_F= 20mA$	-	557	-	nm
Spectrum Bandwidth	$\Delta \lambda$	$I_F= 20mA$	-	30	-	nm
Reverse Current	$I_R$	$V_R=4V$	-	-	10	uA
Half angle	$\theta_{1/2}$	X	-	$\pm 65$	-	deg
		Y	-	$\pm 70$	-	

Characteristic Diagrams

Fig. 1  $I_F - V_F$

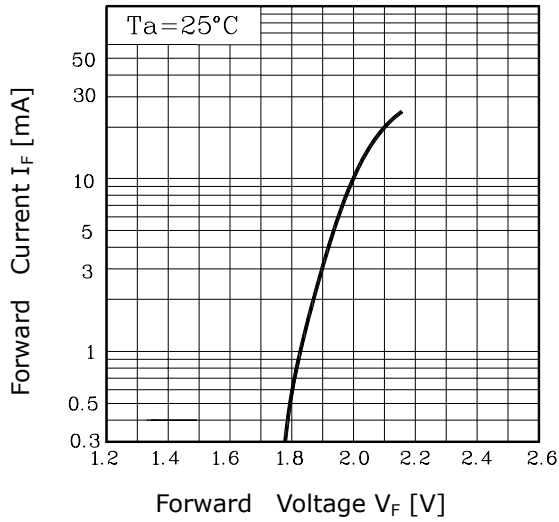


Fig. 2  $I_v - I_F$

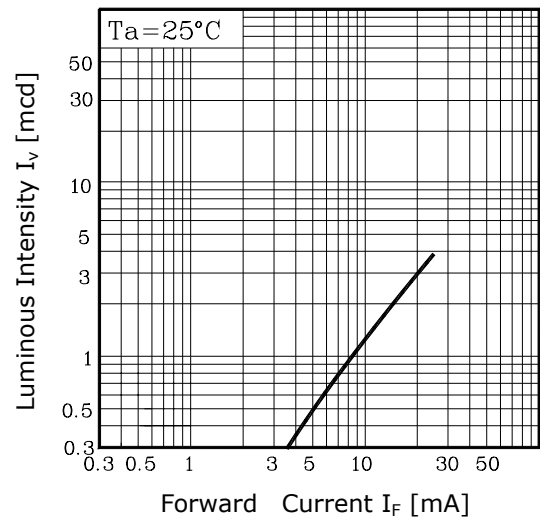


Fig. 3  $I_F - T_a$

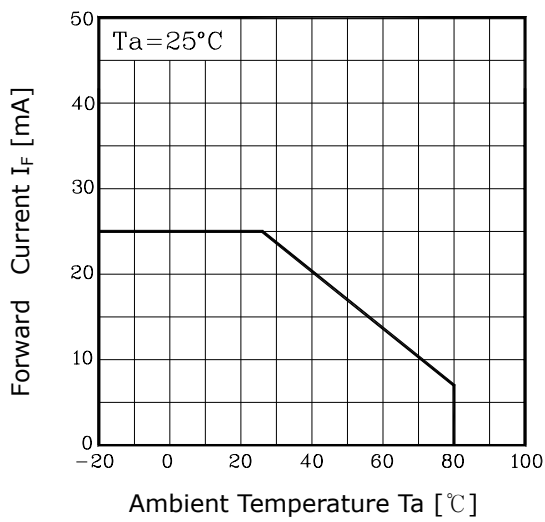


Fig.4 Spectrum Distribution

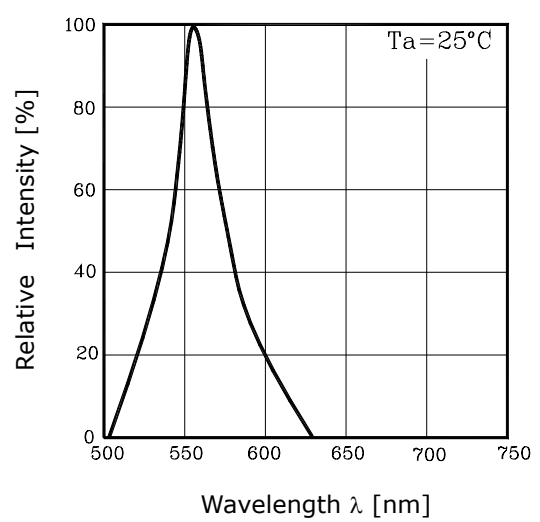


Fig. 5-1 Radiation Diagram(X)

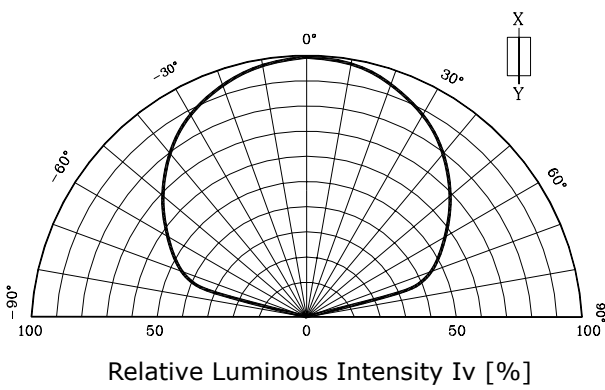


Fig. 5-2 Radiation Diagram(Y)

